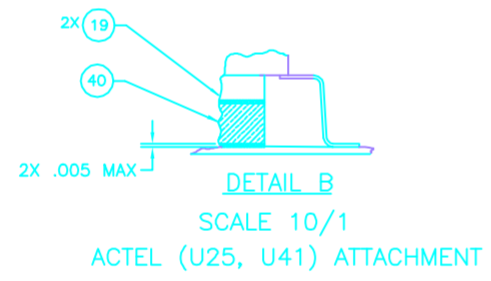
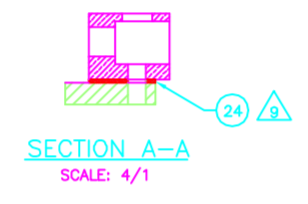


REV.	NO.	DESCRIPTION	CHECKED	APPROVED	DATE
A	36-031	INITIAL RELEASE	FJK	WFM	5/17/96
B	36-045	DELETE R23-27	FJK	RFG	5/31/96
C	36-068	MAX HEIGHT WAS .300	FJK	RFG	6/10/96
D	36-014	ADD ACTEL SHIM			



- NOTES:
- LABEL ASSEMBLY SERIAL NUMBER IN LOCATION SHOWN PER A.W.O. USING F/N 17.
 - RECORD EPOXIES USED, MIX RATIO, EXPIRATION DATES, ETC.
 - SOLDERING TO BE IAW NASA SPECIFICATION NHBS300.4(3A-1).
 - TORQUE J1 TEMPORARY HARDWARE TO 16 IN-OZ PRIOR TO SOLDERING. CENTER CONNECTOR PRIOR TO TORQUING.
 - FORM LEADS IAW 36-02106.
 - DO NOT INSTALL Q1, R23-27.
 - APPLY EPOXY (F/N 19) UNDER U1 (F/N 7001), U2-3 (F/N 7002), U19,20 (F/N 7003).
 - SPOTBOND WITH F/N 15. MIX RATIO: 4g 826V140/2g ALUMINA POWDER. DE-GAS BEFORE APPLYING.
 - SHIM CONNECTOR IAW MIT PROCEDURE 36-02025.
 - TORQUE HARDWARE TO 4 IN-LB PRIOR TO SOLDERING.
 - MASK FOR SOLDER AS INDICATED:
 - RT1-5 BOTH SIDES.
 - CONNECTOR MOUNTING HARDWARE.
 - PLATED MOUNTING HOLES NEAR SIDE.
 - PLATED BAND FAR SIDE.
 - MOUNTING HOLES AND PADS BOTH SIDES FOR Q1.
 - FEED THROUGH E1 BOTH SIDES.
 - SPARE IC SLOTS BOTH SIDES.
 - INSTALL PROTECTIVE COVER, F/N 31, TO J1 PRIOR TO SHIPMENT.
 - CLEAN F/N'S 10,13,14 AND TEMPORARY HARDWARE IAW MIT PROCEDURE 36-02027 PRIOR TO ASSEMBLY.
 - SEE DETAIL B. CENTER F/N 40 ON THE PACKAGE.

